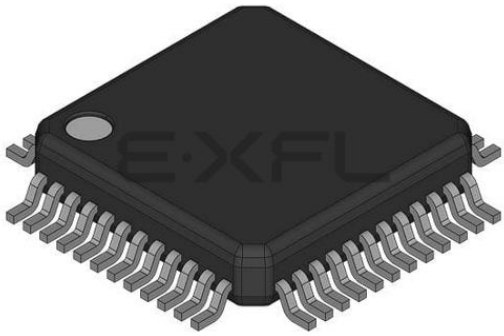

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Details	
Product Status	Active
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Speed	25MHz
Connectivity	CANbus, EBI/EMI, SCI, SPI
Peripherals	POR, PWM, WDT
Number of I/O	31
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12c96cfae

Chapter 5
Interrupt (INTV1) Block Description

Chapter 6
Background Debug Module (BDMV4) Block Description

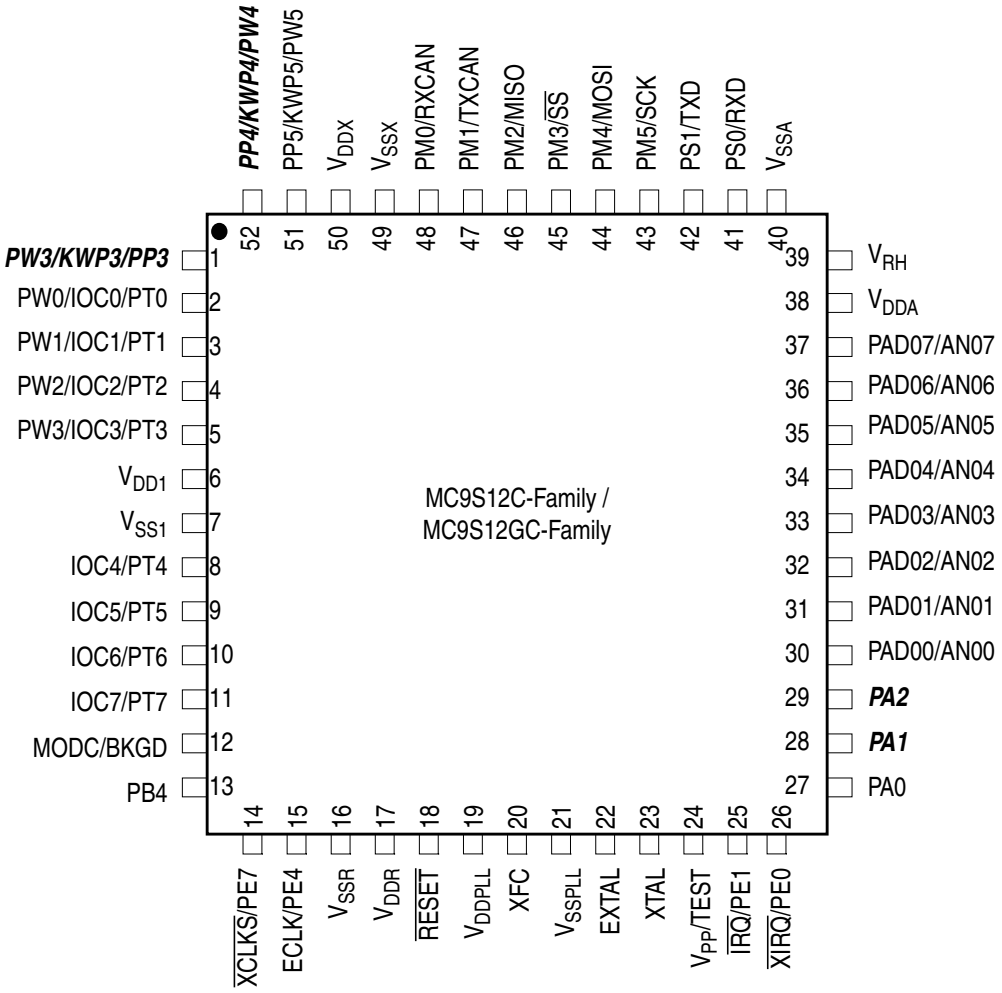
Appendix A
Electrical Characteristics

Appendix B
Emulation Information

Appendix C
Package Information

Appendix D
Derivative Differences

Appendix E
Ordering Information



* Signals shown in ***Bold italic*** are not available on the 48-pin package

Figure 1-8. Pin Assignments in 52-Pin LQFP

2.3.2.5 Port J Registers

2.3.2.5.1 Port J I/O Register (PTJ)

Module Base + 0x0028

	7	6	5	4	3	2	1	0
R	PTJ7	PTJ6	0	0	0	0	0	0
W								
Reset	0	0	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-32. Port J I/O Register (PTJ)

Read: Anytime.

Write: Anytime.

If the data direction bits of the associated I/O pins are set to 1, a read returns the value of the port register, otherwise the value at the pins is read.

2.3.2.5.2 Port J Input Register (PTIJ)

Module Base + 0x0029

	7	6	5	4	3	2	1	0
R	PTIJ7	PTIJ6	0	0	0	0	0	0
W								
Reset	0	0	—	—	—	—	—	—

= Unimplemented or Reserved

Figure 2-33. Port J Input Register (PTIJ)

Read: Anytime.

Write: Never, writes to this register have no effect.

This register always reads back the status of the associated pins. This can be used to detect overload or short circuit conditions on output pins.

4.1.2 Modes of Operation

- Normal expanded wide mode

  Ports A and B are configured as a 16-bit multiplexed address and data bus and port E provides bus control and status signals. This mode allows 16-bit external memory and peripheral devices to be interfaced to the system.
- Normal expanded narrow mode

  Ports A and B are configured as a 16-bit address bus and port A is multiplexed with 8-bit data. Port E provides bus control and status signals. This mode allows 8-bit external memory and peripheral devices to be interfaced to the system.
- Normal single-chip mode

  There is no external expansion bus in this mode. The processor program is executed from internal memory. Ports A, B, K, and most of E are available as general-purpose I/O.
- Special single-chip mode

  This mode is generally used for debugging single-chip operation, boot-strapping, or security related operations. The active background mode is in control of CPU execution and BDM firmware is waiting for additional serial commands through the BKGD pin. There is no external expansion bus after reset in this mode.
- Emulation expanded wide mode

  Developers use this mode for emulation systems in which the users target application is normal expanded wide mode.
- Emulation expanded narrow mode

  Developers use this mode for emulation systems in which the users target application is normal expanded narrow mode.
- Special test mode

  Ports A and B are configured as a 16-bit multiplexed address and data bus and port E provides bus control and status signals. In special test mode, the write protection of many control bits is lifted so that they can be thoroughly tested without needing to go through reset.
- Special peripheral mode

  This mode is intended for Freescale Semiconductor factory testing of the system. The CPU is inactive and an external (tester) bus master drives address, data, and bus control signals.

4.2 External Signal Description

In typical implementations, the MEBI sub-block of the core interfaces directly with external system pins. Some pins may not be bonded out in all implementations.

Table 4-1 outlines the pin names and functions and gives a brief description of their operation reset state of these pins and associated pull-ups or pull-downs is dependent on the mode of operation and on the integration of this block at the chip level (chip dependent).

4.3.2.5 Reserved Registers

Module Base + 0x0004
Starting address location affected by INITRG register setting.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 4-6. Reserved Register

Module Base + 0x0005
Starting address location affected by INITRG register setting.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 4-7. Reserved Register

Module Base + 0x0006
Starting address location affected by INITRG register setting.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 4-8. Reserved Register

Module Base + 0x0007
Starting address location affected by INITRG register setting.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 4-9. Reserved Register

7.3.2.2 Debug Status and Control Register (DBGSC)

Module Base + 0x0021
Starting address location affected by INITRG register setting.

	7	6	5	4	3	2	1	0
R	AF	BF	CF	0	TRG			
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 7-5. Debug Status and Control Register (DBGSC)

Table 7-5. DBGSC Field Descriptions

Field	Description
7 AF	**Trigger A Match Flag** — The AF bit indicates if trigger A match condition was met since arming. This bit is cleared when ARM in DBGC1 is written to a 1 or on any write to this register. 0 Trigger A did not match 1 Trigger A match
6 BF	**Trigger B Match Flag** — The BF bit indicates if trigger B match condition was met since arming.This bit is cleared when ARM in DBGC1 is written to a 1 or on any write to this register. 0 Trigger B did not match 1 Trigger B match
5 CF	**Comparator C Match Flag** — The CF bit indicates if comparator C match condition was met since arming.This bit is cleared when ARM in DBGC1 is written to a 1 or on any write to this register. 0 Comparator C did not match 1 Comparator C match
3:0 TRG	**Trigger Mode Bits** — The TRG bits select the trigger mode of the DBG module as shown Table 7-6. See Section 7.4.2.5, “Trigger Modes,” for more detail.

Table 7-6. Trigger Mode Encoding

TRG Value	Meaning
0000	A only
0001	A or B
0010	A then B
0011	Event only B
0100	A then event only B
0101	A and B (full mode)
0110	A and Not B (full mode)
0111	Inside range
1000	Outside range
1001 ↓ 1111	Reserved (Defaults to A only)

8.4.2.2 General-Purpose Digital Port Operation

The channel pins can be multiplexed between analog and digital data. As analog inputs, they are multiplexed and sampled to supply signals to the A/D converter. Alternatively they can be configured as digital I/O signals with the port I/O data being held in PORTAD.

The analog/digital multiplex operation is performed in the pads. The pad is always connected to the analog inputs of the ATD10B8C. The pad signal is buffered to the digital port registers. This buffer can be turned on or off with the ATDDIEN register. This is important so that the buffer does not draw excess current when analog potentials are presented at its input.

8.4.2.3 Low-Power Modes

The ATD10B8C can be configured for lower MCU power consumption in three different ways:

1. Stop Mode: This halts A/D conversion. Exit from Stop mode will resume A/D conversion, But due to the recovery time the result of this conversion should be ignored.
2. Wait Mode with AWAI = 1: This halts A/D conversion. Exit from Wait mode will resume A/D conversion, but due to the recovery time the result of this conversion should be ignored.
3. Writing ADPU = 0 (Note that all ATD registers remain accessible.): This aborts any A/D conversion in progress.

NOTE

The reset value for the ADPU bit is zero. Therefore, when this module is reset, it is reset into the power down state.

8.5 Initialization/Application Information

8.5.1 Setting up and starting an A/D conversion

The following describes a typical setup procedure for starting A/D conversions. It is highly recommended to follow this procedure to avoid common mistakes.

Each step of the procedure will have a general remark and a typical example

8.5.1.1 Step 1

Power up the ATD and concurrently define other settings in ATDCTL2
Example: Write to ATDCTL2: ADPU=1 -> powers up the ATD, ASCIE=1 enable interrupt on finish of a conversion sequence.

8.5.1.2 Step 2

Wait for the ATD Recovery Time t_{REC} before you proceed with Step 3.

Example: Use the CPU in a branch loop to wait for a defined number of bus clocks.

Table 9-5. PLLCTL Field Descriptions (continued)

Field	Description
5 AUTO	**Automatic Bandwidth Control Bit** — AUTO selects either the high bandwidth (acquisition) mode or the low bandwidth (tracking) mode depending on how close to the desired frequency the VCO is running. Write anytime except when PLLWAI=1, because PLLWAI sets the AUTO bit to 1. 0 Automatic mode control is disabled and the PLL is under software control, using ACQ bit. 1 Automatic mode control is enabled and ACQ bit has no effect.
4 ACQ	**Acquisition Bit** — Write anytime. If AUTO=1 this bit has no effect. 0 Low bandwidth filter is selected. 1 High bandwidth filter is selected.
2 PRE	**RTI Enable during Pseudo-Stop Bit** — PRE enables the RTI during pseudo-stop mode. Write anytime. 0 RTI stops running during pseudo-stop mode. 1 RTI continues running during pseudo-stop mode. **Note:** If the PRE bit is cleared the RTI dividers will go static while pseudo-stop mode is active. The RTI dividers will not initialize like in wait mode with RTIWAI bit set.
1 PCE	**COP Enable during Pseudo-Stop Bit** — PCE enables the COP during pseudo-stop mode. Write anytime. 0 COP stops running during pseudo-stop mode 1 COP continues running during pseudo-stop mode **Note:** If the PCE bit is cleared the COP dividers will go static while pseudo-stop mode is active. The COP dividers will *not* initialize like in wait mode with COPWAI bit set.
0 SCME	**Self-Clock Mode Enable Bit** — Normal modes: Write once —Special modes: Write anytime — SCME can not be cleared while operating in self-clock mode (SCM=1). 0 Detection of crystal clock failure causes clock monitor reset (see Section 9.5.1, “Clock Monitor Reset”). 1 Detection of crystal clock failure forces the MCU in self-clock mode (see Section 9.4.7.2, “Self-Clock Mode”).

9.3.2.8 CRG RTI Control Register (RTICTL)

This register selects the timeout period for the real-time interrupt.

Module Base + 0x0007

	7	6	5	4	3	2	1	0
R	0	RTR6	RTR5	RTR4	RTR3	RTR2	RTR1	RTR0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 9-11. CRG RTI Control Register (RTICTL)

Read: anytime

Write: anytime

NOTE

A write to this register initializes the RTI counter.

Definition." All reset sources are listed in Table 9-13. Refer to the device overview chapter for related vector addresses and priorities.

Table 9-13. Reset Summary

Reset Source	Local Enable
Power-on Reset	None
Low Voltage Reset	None
External Reset	None
Clock Monitor Reset	PLLCTL (CME=1, SCME=0)
COP Watchdog Reset	COPCTL (CR[2:0] nonzero)

The reset sequence is initiated by any of the following events:

- Low level is detected at the $\overline{\text{RESET}}$ pin (external reset).
- Power on is detected.
- Low voltage is detected.
- COP watchdog times out.
- Clock monitor failure is detected and self-clock mode was disabled (SCME = 0).

Upon detection of any reset event, an internal circuit drives the $\overline{\text{RESET}}$ pin low for 128 SYSCLK cycles (see Figure 9-25). Because entry into reset is asynchronous it does not require a running SYSCLK. However, the internal reset circuit of the CRGV4 cannot sequence out of current reset condition without a running SYSCLK. The number of 128 SYSCLK cycles might be increased by n = 3 to 6 additional SYSCLK cycles depending on the internal synchronization latency. After 128+n SYSCLK cycles the $\overline{\text{RESET}}$ pin is released. The reset generator of the CRGV4 waits for additional 64 SYSCLK cycles and then samples the RESET pin to determine the originating source. Table 9-14 shows which vector will be fetched.

Table 9-14. Reset Vector Selection

Sampled $\overline{\text{RESET}}$ Pin (64 Cycles After Release)	Clock Monitor Reset Pending	COP Reset Pending	Vector Fetch
1	0	0	POR / LVR / External Reset
1	1	X	Clock Monitor Reset
1	0	1	COP Reset
0	X	X	POR / LVR / External Reset with rise of $\overline{\text{RESET}}$ pin

NOTE

External circuitry connected to the $\overline{\text{RESET}}$ pin should not include a large capacitance that would interfere with the ability of this signal to rise to a valid logic 1 within 64 SYSCLK cycles after the low drive is released.

13.4 Functional Description

This section provides a complete functional description of the SCI block, detailing the operation of the design from the end user perspective in a number of subsections.

Figure 13-9 shows the structure of the SCI module. The SCI allows full duplex, asynchronous, NRZ serial communication between the CPU and remote devices, including other CPUs. The SCI transmitter and receiver operate independently, although they use the same baud rate generator. The CPU monitors the status of the SCI, writes the data to be transmitted, and processes received data.

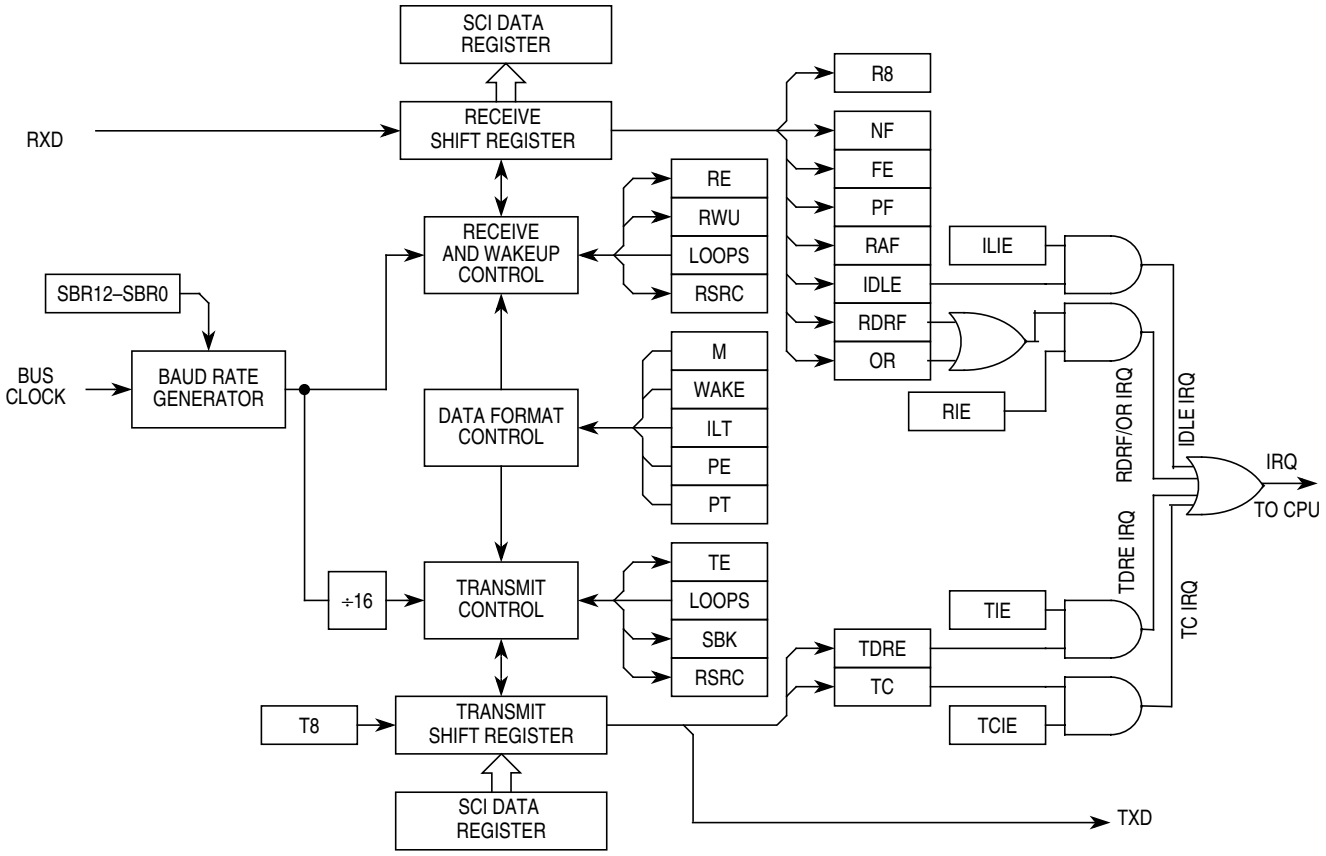


Figure 13-9. SCI Block Diagram

then FCLKDIV register bits PRDIV8 and FDIV[5:0] are to be set as described in Figure 17-21.

For example, if the oscillator clock frequency is 950 kHz and the bus clock is 10 MHz, FCLKDIV bits FDIV[5:0] should be set to 4 (000100) and bit PRDIV8 set to 0. The resulting FCLK is then 190 kHz. As a result, the Flash algorithm timings are increased over optimum target by:

$$(200 - 190) / 200 \times 100 \; = \; 5\%$$

Command execution time will increase proportionally with the period of FCLK.

CAUTION

Because of the impact of clock synchronization on the accuracy of the functional timings, programming or erasing the Flash array cannot be performed if the bus clock runs at less than 1 MHz. Programming or erasing the Flash array with an input clock < 150 kHz should be avoided. Setting FCLKDIV to a value such that FCLK < 150 kHz can destroy the Flash array due to overstress. Setting FCLKDIV to a value such that (1/FCLK + Tbus) < 5µs can result in incomplete programming or erasure of the Flash array cells.

If the FCLKDIV register is written, the bit FDIVLD is set automatically. If the FDIVLD bit is 0, the FCLKDIV register has not been written since the last reset. If the FCLKDIV register has not been written to, the Flash command loaded during a command write sequence will not execute and the ACCERR flag in the FSTAT register will set.

Table 18-2. Flash Array Memory Map Summary

MCU Address Range	PPAGE	Protectable Low Range	Protectable High Range	Array Relative Address[1]
0x4000–0x7FFF	Unpaged (0x3E)	0x4000–0x43FF 0x4000–0x47FF 0x4000–0x4FFF 0x4000–0x5FFF	N.A.	0x18000–0x1BFFF
0x8000–0xBFFF	0x3E	0x8000–0x83FF 0x8000–0x87FF 0x8000–0x8FFF 0x8000–0x9FFF	N.A.	0x18000–0x1BFFF
	0x3F	N.A.	0xB800–0xBFFF 0xB000–0xBFFF 0xA000–0xBFFF 0x8000–0xBFFF	0x1C000–0x1FFFF
0xC000–0xFFFF	Unpaged (0x3F)	N.A.	0xF800–0xFFFF 0xF000–0xFFFF 0xE000–0xFFFF 0xC000–0xFFFF	0x1C000–0x1FFFF

1. Inside Flash block.

18.4.1.2 Command Write Sequence

The Flash command controller is used to supervise the command write sequence to execute program, erase, and erase verify algorithms.

Before starting a command write sequence, the ACCERR and PVIOL flags in the FSTAT register must be clear and the CBEIF flag should be tested to determine the state of the address, data, and command buffers. If the CBEIF flag is set, indicating the buffers are empty, a new command write sequence can be started. If the CBEIF flag is clear, indicating the buffers are not available, a new command write sequence will overwrite the contents of the address, data, and command buffers.

A command write sequence consists of three steps which must be strictly adhered to with writes to the Flash module not permitted between the steps. However, Flash register and array reads are allowed during a command write sequence. The basic command write sequence is as follows:

1. Write to a valid address in the Flash array memory.
2. Write a valid command to the FCMD register.
3. Clear the CBEIF flag in the FSTAT register by writing a 1 to CBEIF to launch the command.

The address written in step 1 will be stored in the FADDR registers and the data will be stored in the FDATA registers. When the CBEIF flag is cleared in step 3, the CCIF flag is cleared by the Flash command controller indicating that the command was successfully launched. For all command write sequences, the CBEIF flag will set after the CCIF flag is cleared indicating that the address, data, and command buffers are ready for a new command write sequence to begin. A buffered command will wait for the active operation to be completed before being launched. Once a command is launched, the completion of the command operation is indicated by the setting of the CCIF flag in the FSTAT register. The CCIF flag will set upon completion of all active and buffered commands.

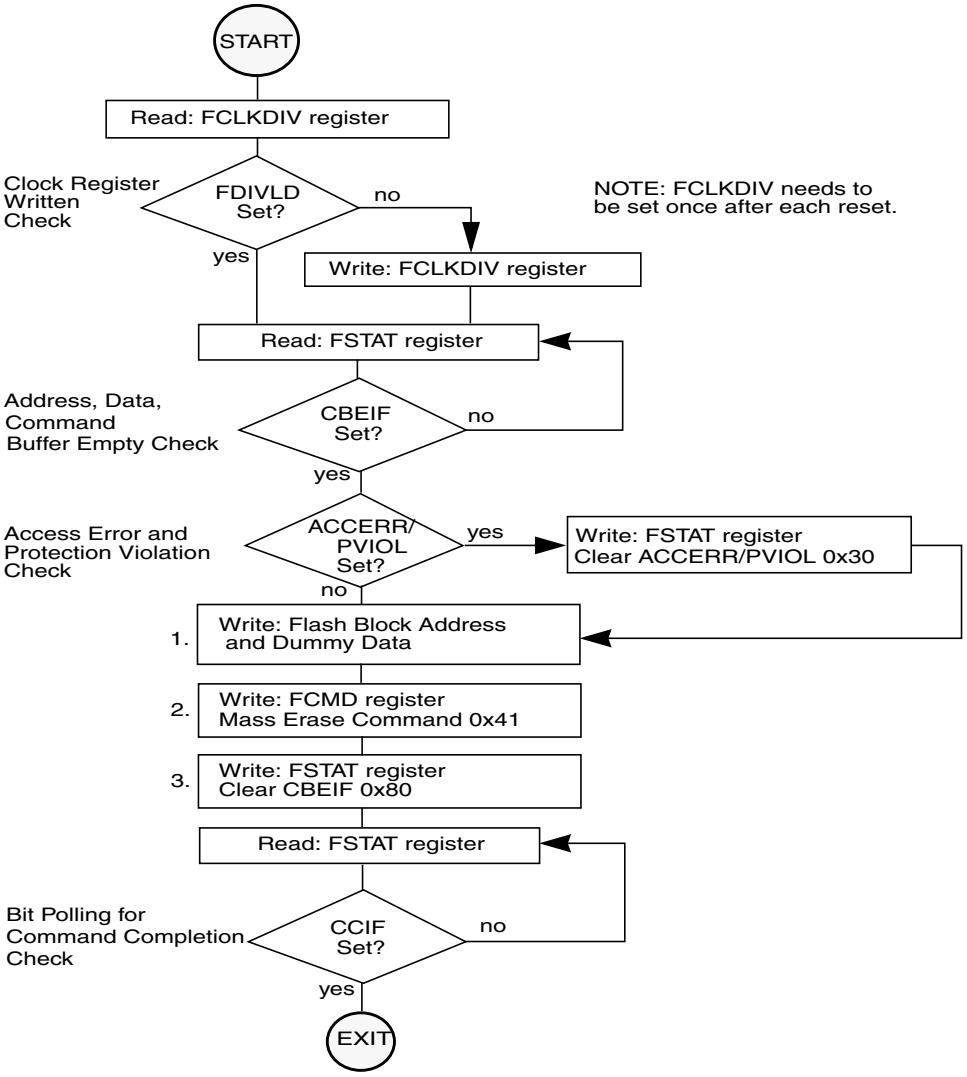


Figure 18-25. Example Mass Erase Command Flow

Table 19-5. FSEC Field Descriptions

Field	Description
7–6 KEYEN[1:0]	**Backdoor Key Security Enable Bits** — The KEYEN[1:0] bits define the enabling of the backdoor key access to the Flash module as shown in Table 19-6.
5–2 NV[5:2]	**Nonvolatile Flag Bits** — The NV[5:2] bits are available to the user as nonvolatile flags.
1–0 SEC[1:0]	**Flash Security Bits** — The SEC[1:0] bits define the security state of the MCU as shown in Table 19-7. If the Flash module is unsecured using backdoor key access, the SEC[1:0] bits are forced to 1:0.

Table 19-6. Flash KEYEN States

KEYEN[1:0]	Status of Backdoor Key Access
00	DISABLED
01(1)	DISABLED
10	ENABLED
11	DISABLED

1. Preferred KEYEN state to disable Backdoor Key Access.

Table 19-7. Flash Security States

SEC[1:0]	Status of Security
00	Secured
01(1)	Secured
10	Unsecured
11	Secured

1. Preferred SEC state to set MCU to secured state.

The security function in the Flash module is described in Section 19.4.3, “Flash Module Security”.

19.3.2.3 RESERVED1

This register is reserved for factory testing and is not accessible to the user.

Module Base + 0x0002

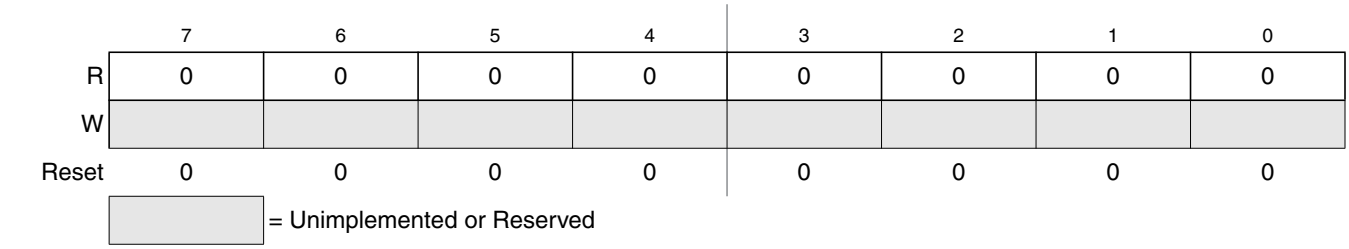


Figure 19-8. RESERVED1

All bits read 0 and are not writable.

FPHDIS is cleared. The FPROT register is loaded from Flash address 0xFF0D during the reset sequence, indicated by F in Figure 19-10.

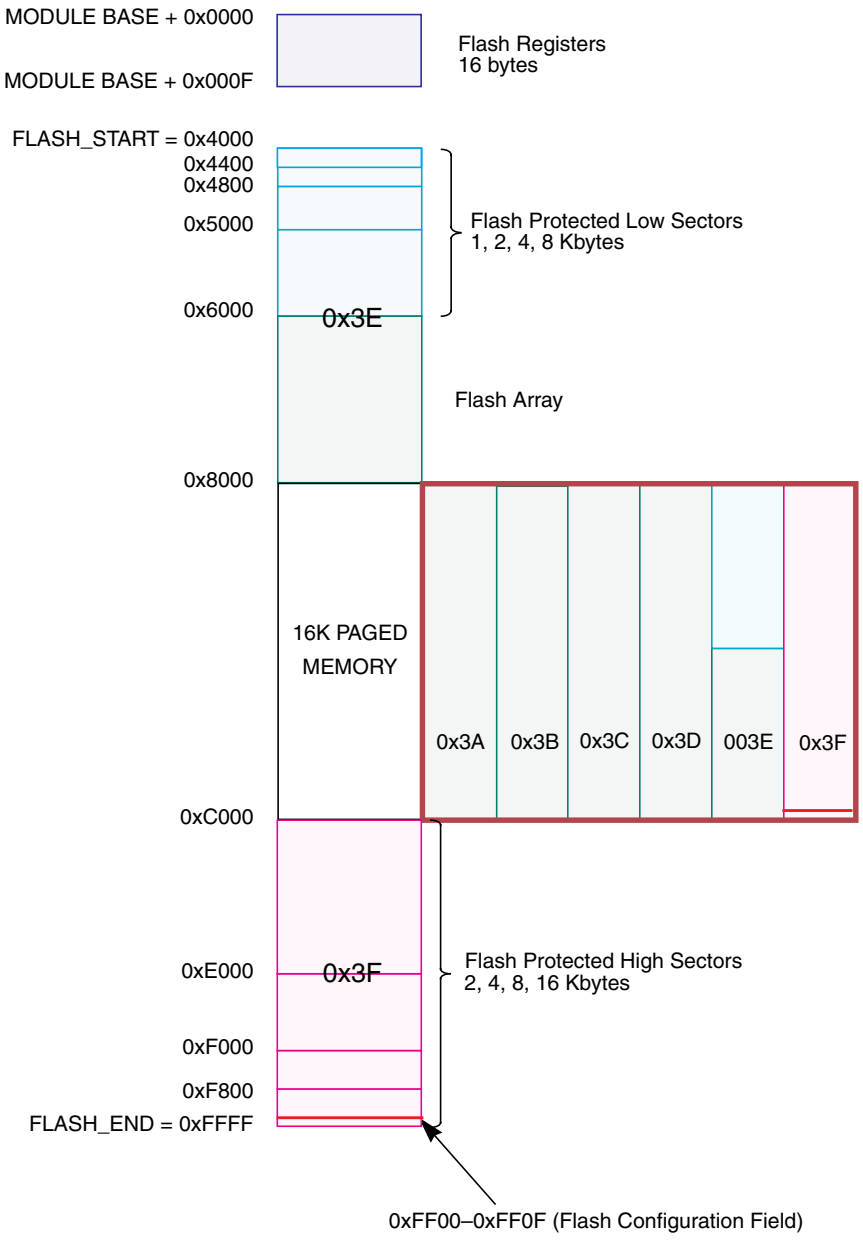
To change the Flash protection that will be loaded on reset, the upper sector of the Flash array must be unprotected, then the Flash protection byte located at Flash address 0xFF0D must be written to.

A protected Flash sector is disabled by FPHDIS and FPLDIS while the size of the protected sector is defined by FPHS[1:0] and FPLS[1:0] in the FPROT register.

Trying to alter any of the protected areas will result in a protect violation error and the PVIOL flag will be set in the FSTAT register (see Section 19.3.2.6). A mass erase of the whole Flash array is only possible when protection is fully disabled by setting the FPOPEN, FPLDIS, and FPHDIS bits. An attempt to mass erase a Flash array while protection is enabled will set the PVIOL flag in the FSTAT register.

Table 19-9. FPROT Field Descriptions

Field	Description
7 FPOPEN	**Protection Function for Program or Erase** — It is possible using the FPOPEN bit to either select address ranges to be protected using FPHDIS, FPLDIS, FPHS[1:0] and FPLS[1:0] or to select the same ranges to be unprotected. When FPOPEN is set, FPxDIS enables the ranges to be protected, whereby clearing FPxDIS enables protection for the range specified by the corresponding FPxS[1:0] bits. When FPOPEN is cleared, FPxDIS defines unprotected ranges as specified by the corresponding FPxS[1:0] bits. In this case, setting FPxDIS enables protection. Thus the effective polarity of the FPxDIS bits is swapped by the FPOPEN bit as shown in Table 19-10. This function allows the main part of the Flash array to be protected while a small range can remain unprotected for EEPROM emulation. 0 The FPHDIS and FPLDIS bits define Flash address ranges to be unprotected 1 The FPHDIS and FPLDIS bits define Flash address ranges to be protected
6 NV6	**Nonvolatile Flag Bit** — The NV6 bit should remain in the erased state for future enhancements.
5 FPHDIS	**Flash Protection Higher Address Range Disable** — The FPHDIS bit determines whether there is a protected/unprotected area in the higher space of the Flash address map. 0 Protection/unprotection enabled 1 Protection/unprotection disabled
4–3 FPHS[1:0]	**Flash Protection Higher Address Size** — The FPHS[1:0] bits determine the size of the protected/unprotected sector as shown in Table 19-11. The FPHS[1:0] bits can only be written to while the FPHDIS bit is set.
2 FPLDIS	**Flash Protection Lower Address Range Disable** — The FPLDIS bit determines whether there is a protected/unprotected sector in the lower space of the Flash address map. 0 Protection/unprotection enabled 1 Protection/unprotection disabled
1–0 FPLS[1:0]	**Flash Protection Lower Address Size** — The FPLS[1:0] bits determine the size of the protected/unprotected sector as shown in Table 19-12. The FPLS[1:0] bits can only be written to while the FPLDIS bit is set.



Note: 0x3A–0x3F correspond to the PPAGE register content

Figure 20-4. Flash Memory Map

Module Base + 0x000C

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 20-19. RESERVED3

All bits read 0 and are not writable.

20.3.2.12 RESERVED4

This register is reserved for factory testing and is not accessible to the user.

Module Base + 0x000D

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 20-20. RESERVED4

All bits read 0 and are not writable.

20.3.2.13 RESERVED5

This register is reserved for factory testing and is not accessible to the user.

Module Base + 0x000E

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 20-21. RESERVED5

All bits read 0 and are not writable.

20.3.2.14 RESERVED6

This register is reserved for factory testing and is not accessible to the user.

A.2.2 ATD Operating Characteristics In 3.3V Range

The Table A-11 shows conditions under which the ATD operates.

The following constraints exist to obtain full-scale, full range results: $V_{SSA} \le V_{RL} \le V_{IN} \le V_{RH} \le V_{DDA}$. This constraint exists since the sample buffer amplifier can not drive beyond the power supply levels that it ties to. If the input level goes outside of this range it will effectively be clipped

Table A-11. ATD Operating Characteristics

Conditions are shown in Table A-4 unless otherwise noted; Supply Voltage 3.3V-10% <= V_{DDA} <= 3.3V+10%							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	D	Reference Potential Low High	 V_{RL} V_{RH}	 V_{SSA} $V_{DDA}/2$	 — —	 $V_{DDA}/2$ V_{DDA}	 V V
2	C	Differential Reference Voltage	V_{RH}-V_{RL}	3.0	3.3	3.6	V
3	D	ATD Clock Frequency	f_{ATDCLK}	0.5	—	2.0	MHz
4	D	ATD 10-Bit Conversion Period Clock Cycles(1) Conv, Time at 2.0MHz ATD Clock f_{ATDCLK}	 N_{CONV10} T_{CONV10}	 14 7	 — —	 28 14	 Cycles µs
5	D	ATD 8-Bit Conversion Period Clock Cycles1 Conv, Time at 2.0MHz ATD Clock f_{ATDCLK}	 N_{CONV8} T_{CONV8}	 12 6	 — —	 26 13	 Cycles µs
6	D	Recovery Time (V_{DDA}=3.3 Volts)	t_{REC}	—	—	20	µs
7	P	Reference Supply current	I_{REF}	—	—	0.250	mA

1. The minimum time assumes a final sample period of 2 ATD clocks cycles while the maximum time assumes a final sample period of 16 ATD clocks.

A.2.3 Factors Influencing Accuracy

Three factors — source resistance, source capacitance and current injection — have an influence on the accuracy of the ATD.

A.2.3.1 Source Resistance

Due to the input pin leakage current as specified in Table A-6 in conjunction with the source resistance there will be a voltage drop from the signal source to the ATD input. The maximum source resistance R_S specifies results in an error of less than 1/2 LSB (2.5mV) at the maximum leakage current. If device or operating conditions are less than worst case or leakage-induced error is acceptable, larger values of source resistance is allowable.

A.2.3.2 Source Capacitance

When sampling an additional internal capacitor is switched to the input. This can cause a voltage drop due to charge sharing with the external and the pin capacitance. For a maximum sampling error of the input voltage ≤ 1LSB, then the external filter capacitor, $C_f \ge 1024 * (C_{INS} - C_{INN})$.